



Material Content Data Sheet



Sales Product Name		BC 857BL3 E6327		Issued		19. July 2018		
MA#		MA000081590						
Package		PG-TSLP-3-1		Weight*		0.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.15		1505	
	noble metal	gold	7440-57-5	0.003	0.58		5836	
	inorganic material	silicon	7440-21-3	0.039	7.12	7.85	71232	78573
leadframe	non noble metal	nickel	7440-02-0	0.071	12.97	12.97	129711	129711
wire	noble metal	gold	7440-57-5	0.012	2.16	2.16	21595	21595
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		371	
	organic material	carbon black	1333-86-4	0.004	0.74		7421	
	plastics	epoxy resin	-	0.055	10.02		100175	
	inorganic material	silicondioxide	60676-86-0	0.348	63.42	74.22	634072	742039
leadfinish	noble metal	gold	7440-57-5	0.008	1.40	1.40	14041	14041
plating	noble metal	gold	7440-57-5	0.008	1.40	1.40	14041	14041
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com